

Final Product Change Notification

Issue Date: 19-Jun-2020 Effective Date: 17-Sep-2020

Dear Emma Tempest,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to <u>view this</u> notification online

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Management Summary

Enable ATKH as 2nd source to support NX20P3483UK manufacture of WT and BE2(grinding/sawing/marking and packing) from ASEK to ATKH.

Change Category	-,			
[] Wafer Fab Process	[] Assembly Process	[] Product Marking	[X] Test Location	[] Design
[] Wafer Fab Materials	[] Assembly Materials	[] Mechanical Specification	[]Test Process	[] Errata
[] Wafer Fab Location	[] Assembly Location	[X] Packing/Shipping/Labeling	[] Test j Equipment	[] Electrical spec./Test coverage

[X] Other - Grinding/Sawing/Packing

FPCN: ASEK WT/Grinding/Sawing 2nd Source to ATKH -NX20P3483UK

Description of Change

[] Firmware

Expanding the current flow which is currently limited to an ASE Assembly to allow for ATKH WT and BE2. The flow allows for manufacturing flexibility and helps ensure customer supply.

WT and BE2(back half of the Assembly process) (grinding/sawing/marking and Packing) will be enabled in ATKH.

13" packing reel has been implemented with new 12NC introduced: 9353 576 66019

Reason for Change

Expanding the current flow which is currently limited to an ASE Assembly to allow for ATKH WT and BE2. The flow allows for manufacturing flexibility and helps ensure customer supply.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 06-Jul-2020

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

WT and BE2 Expansion. No Depletion of Inventory required.

Additional information

Affected products and sales history information: see attached file

Self qualification: <u>view online</u>
Additional documents: <u>view online</u>

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 19-Jul-2020.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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